

Semiconductor and IC Packaging Materials Market - 2023-2031

<https://marketpublishers.com/r/S528835F686EEN.html>

Date: August 2026

Pages: 218

Price: US\$ 2,999.00 (Single User License)

ID: S528835F686EEN

Abstracts

The Semiconductor and IC Packaging Materials Market was valued at US\$ 43.1 billion in 2023 and is anticipated to reach US\$ 93.7 billion by 2031, at a CAGR of 0.102 from 2026 to 2032.

The report delivers in-depth insights into key market dynamics, including regional growth trends, market segmentation, CAGR projections, and the revenue performance of leading industry players. It also highlights major growth drivers shaping the market landscape. Designed to provide a clear and comprehensive perspective, the report offers a detailed view of the current market size in terms of both value and volume, along with emerging opportunities and the overall development outlook of the Semiconductor and IC Packaging Materials Market.

This report delivers a comprehensive overview of the Semiconductor and IC Packaging Materials Market, with both quantitative and qualitative analyses, to help readers develop growth strategies, assess the competitive landscape, evaluate their position in the current market, and make informed business decisions regarding Semiconductor and IC Packaging Materials Market. The Semiconductor and IC Packaging Materials Market size, estimates, and forecasts are provided in terms of output/shipments (K MT) and revenue (US\$ millions), with 2025 as the base year and historical and forecast data for 2023–2031.

Semiconductor and IC Packaging Materials Market Scope:

By Type

Organic Substrates

Bonding Wires

Leadframes

Ceramic Packages

Die Attach Materials

Thermal Interface Materials

Solder Balls

Encapsulation Resins

Others

By Technology

Grid Array

Wafer-level Packaging

Small-outline Package (SOP)

Flat no-leads Packages

Dual In-line Packages

3D Packaging

Others

By End-User

Consumer Electronics

Automotive

Healthcare

IT & Telecommunication

Aerospace and Defense

Others

Key Players

Intel

Amkor Technology

Deca Technologies

Siemens

Samsung

Advanced Semiconductor Engineering Inc

Taiwan Semiconductor Manufacturing Company

Microchip Technology

Synapse Electronique

FlipChip International LLC

Major Highlights

This report delivers a comprehensive overview of the Semiconductor and IC Packaging Materials Market, with both quantitative and qualitative analyses, to help readers develop growth strategies, assess the competitive landscape, evaluate their position in the current market, and make informed business decisions regarding Semiconductor and IC Packaging Materials Market. The Semiconductor and IC Packaging Materials Market size, estimates, and forecasts are provided in terms of output/shipments (K Sqm) and revenue (US\$ millions), with 2025 as the base year and historical and forecast data for 2023–2031.

This report will assist keyword manufacturers, new entrants, and companies across the industry value chain with information on revenues, production, and average prices for the overall market and its sub-segments, by company, by Type, by Application, and by region.

Regional Analysis:

North America (U.S., Canada, Mexico)

Europe (U.K., Italy, Germany, Russia, France, Spain, The Netherlands and Rest of Europe)

Asia-Pacific (India, Japan, China, South Korea, Australia, Indonesia Rest of Asia Pacific)

South America (Colombia, Brazil, Argentina, Rest of South America)

Middle East & Africa (Saudi Arabia, U.A.E., South Africa, Rest of Middle East & Africa)

Partner Identification

Increase Your Customer Base by 3X using our Partner Identification tool

Uncover strategic collaboration opportunities with DataM vetted partners aligned to your ecosystem.

Identify high potential M&A targets based on synergies, market positioning and growth trajectory.

Prioritize partners by strategic fit rather than general capability.

Why Choose DataM?

Data-Driven Insights: Dive into detailed analyses with granular insights such as pricing, market shares and value chain evaluations, enriched by interviews with industry leaders and disruptors.

Post-Purchase Support and Expert Analyst Consultations: As a valued client, gain direct access to our expert analysts for personalized advice and strategic guidance, tailored to your specific needs and challenges.

White Papers and Case Studies: Benefit quarterly from our in-depth studies related to your purchased titles, tailored to refine your operational and marketing strategies for maximum impact.

Annual Updates on Purchased Reports: As an existing customer, enjoy the privilege of annual updates to your reports, ensuring you stay abreast of the latest market insights and technological advancements. Terms and conditions apply.

Specialized Focus on Emerging Markets: DataM differentiates itself by delivering in-depth, specialized insights specifically for emerging markets, rather than offering generalized geographic overviews. This approach equips our clients with a nuanced understanding and actionable intelligence that are essential for navigating and succeeding in high-growth regions.

Value of DataM Reports: Our reports offer specialized insights tailored to the latest trends and specific business inquiries. This personalized approach provides a deeper, strategic perspective, ensuring you receive the precise information necessary to make informed decisions. These insights complement and go beyond what is typically available in generic databases.

Target Audience 2026

Manufacturers/ Buyers

Industry Investors/Investment Bankers

Research Professionals

Emerging Companies

Contents

1. METHODOLOGY AND SCOPE

- 1.1. Research Methodology
- 1.2. Research Objective and Scope of the Report

2. DEFINITION AND OVERVIEW

3. EXECUTIVE SUMMARY

- 3.1. Snippet by Type
- 3.2. Snippet by Technology
- 3.3. Snippet by End-User
- 3.4. Snippet by Region

4. DYNAMICS

- 4.1. Impacting Factors
 - 4.1.1. Drivers
 - 4.1.1.1. Technological Advancements for High-Performance Semiconductors
 - 4.1.1.2. Rising Demand for Consumer Electronics
 - 4.1.2. Restraints
 - 4.1.2.1. High Costs
 - 4.1.3. Opportunity
 - 4.1.4. Impact Analysis

5. INDUSTRY ANALYSIS

- 5.1. Porter's Five Force Analysis
- 5.2. Supply Chain Analysis
- 5.3. Pricing Analysis
- 5.4. Regulatory Analysis
- 5.5. Russia-Ukraine War Impact Analysis
- 5.6. DMI Opinion

6. COVID-19 ANALYSIS

- 6.1. Analysis of COVID-19

- 6.1.1. Scenario Before COVID-19
- 6.1.2. Scenario During COVID-19
- 6.1.3. Scenario Post COVID-19
- 6.2. Pricing Dynamics Amid COVID-19
- 6.3. Demand-Supply Spectrum
- 6.4. Government Initiatives Related to the Market During Pandemic
- 6.5. Manufacturers Strategic Initiatives
- 6.6. Conclusion

7. BY TYPE

- 7.1. Introduction
 - 7.1.1. Market Size Analysis and Y-o-Y Growth Analysis (%), By Type
 - 7.1.2. Market Attractiveness Index, By Type
- 7.2. Organic Substrates*
 - 7.2.1. Introduction
 - 7.2.2. Market Size Analysis and Y-o-Y Growth Analysis (%)
- 7.3. Bonding Wires
- 7.4. Leadframes
- 7.5. Ceramic Packages
- 7.6. Die Attach Materials
- 7.7. Thermal Interface Materials
- 7.8. Solder Balls
- 7.9. Encapsulation Resins
- 7.10. Others

8. BY TECHNOLOGY

- 8.1. Introduction
 - 8.1.1. Market Size Analysis and Y-o-Y Growth Analysis (%), By Technology
 - 8.1.2. Market Attractiveness Index, By Technology
- 8.2. Grid Array*
 - 8.2.1. Introduction
 - 8.2.2. Market Size Analysis and Y-o-Y Growth Analysis (%)
- 8.3. Wafer-level Packaging
- 8.4. Small-outline Package (SOP)
- 8.5. Flat no-leads Packages
- 8.6. Dual In-line Packages
- 8.7. 3D Packaging

8.8. Others

9. BY END-USER

9.1. Introduction

9.1.1. Market Size Analysis and Y-o-Y Growth Analysis (%), By End-User

9.1.2. Market Attractiveness Index, By End-User

9.2. Consumer Electronics*

9.2.1. Introduction

9.2.2. Market Size Analysis and Y-o-Y Growth Analysis (%)

9.3. Automotive

9.4. Healthcare

9.5. IT & Telecommunication

9.6. Aerospace and Defense

9.7. Others

10. BY REGION

10.1. Introduction

10.1.1. Market Size Analysis and Y-o-Y Growth Analysis (%), By Region

10.1.2. Market Attractiveness Index, By Region

10.2. North America

10.2.1. Introduction

10.2.2. Key Region-Specific Dynamics

10.2.3. Market Size Analysis and Y-o-Y Growth Analysis (%), By Type

10.2.4. Market Size Analysis and Y-o-Y Growth Analysis (%), By Technology

10.2.5. Market Size Analysis and Y-o-Y Growth Analysis (%), By End-User

10.2.6. Market Size Analysis and Y-o-Y Growth Analysis (%), By Country

10.2.6.1. U.S.

10.2.6.2. Canada

10.2.6.3. Mexico

10.3. Europe

10.3.1. Introduction

10.3.2. Key Region-Specific Dynamics

10.3.3. Market Size Analysis and Y-o-Y Growth Analysis (%), By Type

10.3.4. Market Size Analysis and Y-o-Y Growth Analysis (%), By Technology

10.3.5. Market Size Analysis and Y-o-Y Growth Analysis (%), By End-User

10.3.6. Market Size Analysis and Y-o-Y Growth Analysis (%), By Country

10.3.6.1. Germany

- 10.3.6.2. UK
- 10.3.6.3. France
- 10.3.6.4. Italy
- 10.3.6.5. Russia
- 10.3.6.6. Rest of Europe
- 10.4. South America
 - 10.4.1. Introduction
 - 10.4.2. Key Region-Specific Dynamics
 - 10.4.3. Market Size Analysis and Y-o-Y Growth Analysis (%), By Type
 - 10.4.4. Market Size Analysis and Y-o-Y Growth Analysis (%), By Technology
 - 10.4.5. Market Size Analysis and Y-o-Y Growth Analysis (%), By End-User
 - 10.4.6. Market Size Analysis and Y-o-Y Growth Analysis (%), By Country
 - 10.4.6.1. Brazil
 - 10.4.6.2. Argentina
 - 10.4.6.3. Rest of South America
- 10.5. Asia-Pacific
 - 10.5.1. Introduction
 - 10.5.2. Key Region-Specific Dynamics
 - 10.5.3. Market Size Analysis and Y-o-Y Growth Analysis (%), By Type
 - 10.5.4. Market Size Analysis and Y-o-Y Growth Analysis (%), By Technology
 - 10.5.5. Market Size Analysis and Y-o-Y Growth Analysis (%), By End-User
 - 10.5.6. Market Size Analysis and Y-o-Y Growth Analysis (%), By Country
 - 10.5.6.1. China
 - 10.5.6.2. India
 - 10.5.6.3. Japan
 - 10.5.6.4. Australia
 - 10.5.6.5. Rest of Asia-Pacific
- 10.6. Middle East and Africa
 - 10.6.1. Introduction
 - 10.6.2. Key Region-Specific Dynamics
 - 10.6.3. Market Size Analysis and Y-o-Y Growth Analysis (%), By Type
 - 10.6.4. Market Size Analysis and Y-o-Y Growth Analysis (%), By Technology
 - 10.6.5. Market Size Analysis and Y-o-Y Growth Analysis (%), By End-User

11. COMPETITIVE LANDSCAPE

- 11.1. Competitive Scenario
- 11.2. Market Positioning/Share Analysis
- 11.3. Mergers and Acquisitions Analysis

12. COMPANY PROFILES

12.1. Intel*

12.1.1. Company Overview

12.1.2. Product Portfolio and Description

12.1.3. Financial Overview

12.1.4. Key Developments

12.2. Amkor Technology

12.3. Deca Technologies

12.4. Siemens

12.5. Samsung

12.6. Advanced Semiconductor Engineering Inc

12.7. Taiwan Semiconductor Manufacturing Company

12.8. Microchip Technology

12.9. Synapse Electronique

12.10. FlipChip International LLC (LIST NOT EXHAUSTIVE)

13. APPENDIX

13.1. About Us and Services

13.2. Contact Us

I would like to order

Product name: Semiconductor and IC Packaging Materials Market - 2023-2031

Product link: <https://marketpublishers.com/r/S528835F686EEN.html>

Price: US\$ 2,999.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/S528835F686EEN.html>